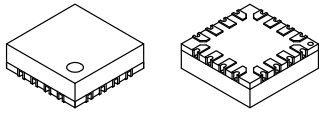


MECHANICAL CASE OUTLINE

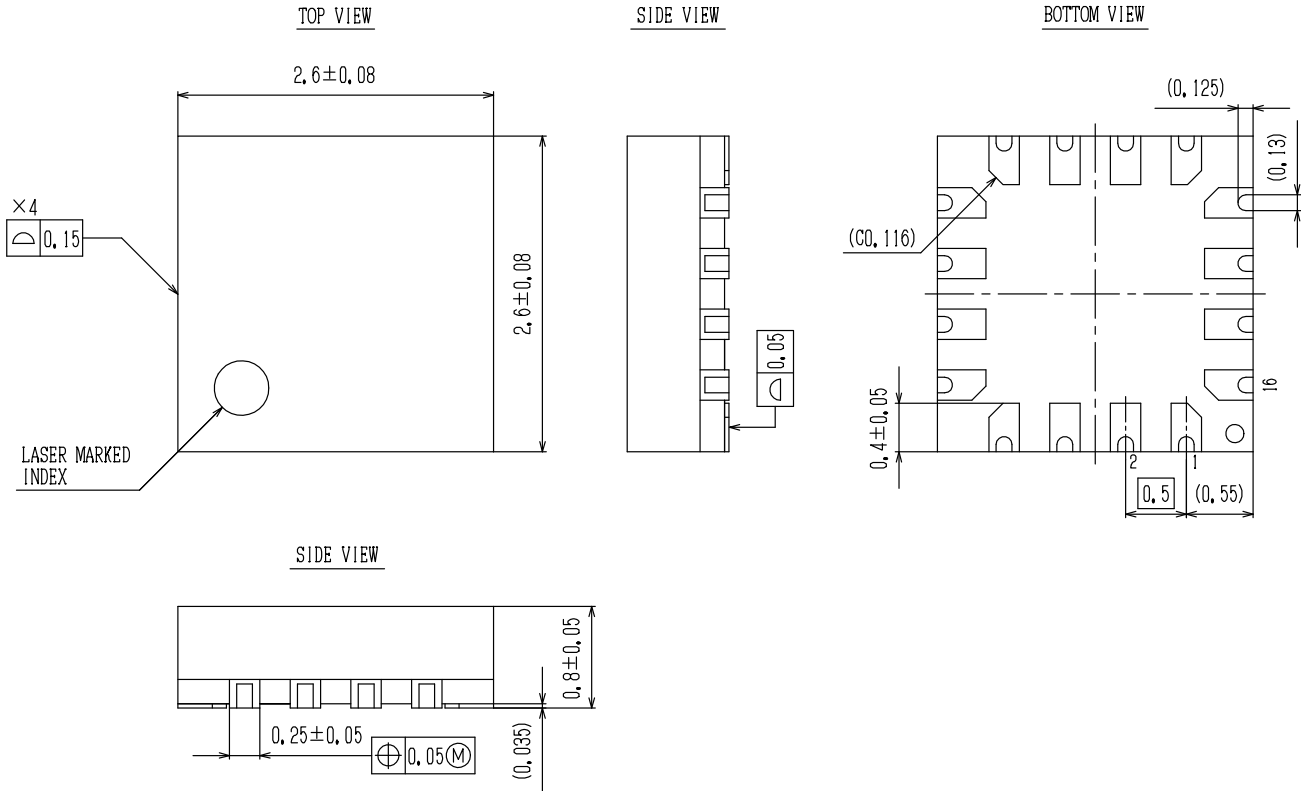
PACKAGE DIMENSIONS

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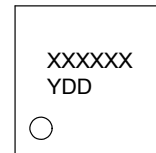
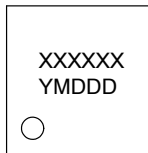


VCT16 2.6x2.6, 0.5P
CASE 601AA
ISSUE A

DATE 15 NOV 2013



GENERIC MARKING DIAGRAM*



XXXXXX = Specific Device Code
 Y = Year
 M = Month
 DDD = Additional Traceability Data

XXXXXX = Specific Device Code
 Y = Year
 DD = Additional Traceability Data

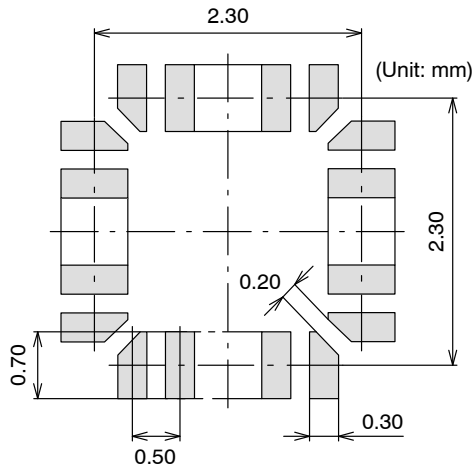
*This information is generic. Please refer to device data sheet for actual part marking.
 Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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VCT16 2.6x2.6, 0.5P
CASE 601AA
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SOLDERING FOOTPRINT*



NOTE: The measurements are not to guarantee but for reference only.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	VCT16 2.6X2.6, 0.5P	PAGE 2 OF 3

